

RV1S9960A

R08DS0169EJ0200 Rev.2.00 Jun. 30, 2021

HIGH CMR, 15Mbps CMOS OUTPUT, LOW FORWARD-CURRENT(IF) 3.3V/5V OPERATION, 15 mm LONG-CREEPAGE 8-PIN LSDIP

DESCRIPTION

The RV1S9960A is a photocoupler featuring high-speed switching up to 15Mbps with active low output logic which consist of an AlGaAs LED on the input side and an integrated circuit with a photodiode on the output.

This product enables to low current operation on 3.3V/5V power supply with high noise-tolerant CMR:50kV/us min. and high temperature operation up to $T_A = 110^{\circ}$ C in logic interface circuit.

FEATURES

- Long creepage distance (15 mm MIN)
- High speed communication (15 Mbps)
- High temperature operation (-40 to +110 °C)
- High common mode (dv/dt) tolerant (CM_H, CM_L = \pm 50 kV/ μ s MIN.)
- High isolation voltage (BV = 7 500 Vr.m.s.)
- Low input drive current (IFHL = 3.8 mA MAX.)
- Low voltage power supply operation (V_{DD} = 2.7 V ~ 5.5 V)
- Low pulse width distortion (PWD = 20 ns MAX.)
- Ordering number of tape product :

RV1S9960ACCSP-10Yx#KC0: 1 000 pcs/reel

- Pb free product
- Safety standards approval

UL: UL1577, Double protection

CSA: CAN/CSA-C22.2 No.62368-1, Reinforced insulation

VDE: DIN EN 60747-5-5 (Option)

PIN CONNECTION (Top View) 8 7 6 5 2. Anode 3. Cathode 4. NC 5. GND 6. Vo 7. NC 8. VDD

TRUTH TABLE

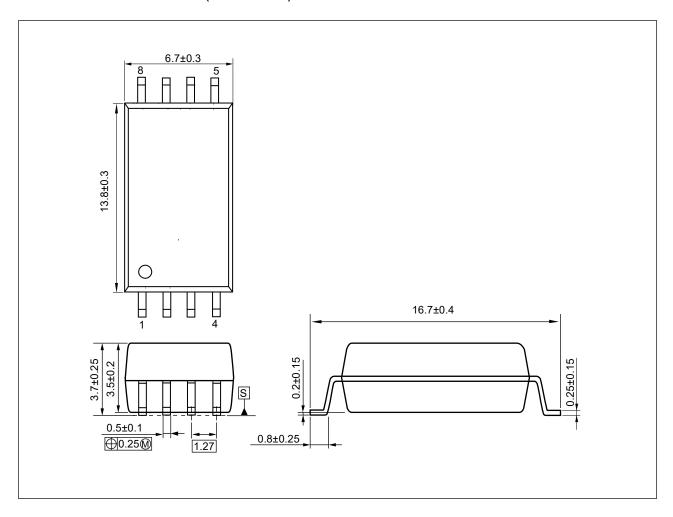
LED	OUTPUT
ON	L
OFF	Н

APPLICATIONS

- Industrial Inverter
- Solar Inverter
- Power Conditioner

Start of mass production Jun.2019

PACKAGE DIMENSIONS (UNIT: mm)

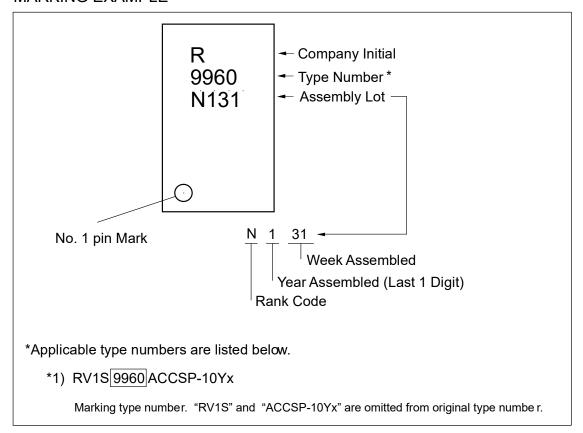


Weight: 0.642g (typ.)

PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	14.5 mm
Creepage Distance	15 mm
Isolation Distance	0.4 mm

MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating	Packing Style	Safety Standard	Application
		Specification		Approval	Part Number*1
RV1S9960ACCSP-	RV1S9960ACCSP	Pb-Free and	10 pcs	Standard products	RV1S9960A
10YC	-10YC#SC0	Halogen Free	(Tape 10 pcs cut)	(UL, CSA approved)	
	RV1S9960ACCSP	(Ni/Pd/Au)	Embossed Tape 1 000		
	-10YC#KC0		pcs/reel		
RV1S9960ACCSP-	RV1S9960ACCSP		10 pcs	UL, CSA,	
10YV	-10YV#SC0		(Tape 10 pcs cut)	DIN EN 60747-5-5	
	RV1S9960ACCSP		Embossed Tape 1 000	approved	
	-10YV#KC0		pcs/reel		

Notes: *1. For the application of the Safety Standard, following part number should be used.

ABSOLUTELY MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	lF	20	mA
	Reverse Voltage	VR	5	V
Detector	Supply Voltage	V _{DD}	6	V
	Output Voltage	Vo	6	V
	Output Current	lo	10	mA
	Power Dissipation *1	Pc	250	mW
Isolation Voltage*2		BV	7 500	Vr.m.s.
Operating Ambient Temperature		TA	-40 to +110	°C
Storage Temperature		T _{stg}	-55 to +125	°C

Notes: 1. Reduced to 5.0 mW/°C at T_A = 85 °C or more

2. AC Voltage for 1minite at T_A = 25 °C, RH = 60 % between input and output. Pins 1-4 shorted together, 5-8 shorted together.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Low Level forward voltage	V _{FL}	0		8.0	V
High Level Forward Current	I _{FH}	5		8	mA
Supply Voltage	V_{DD}	2.7		5.5	V

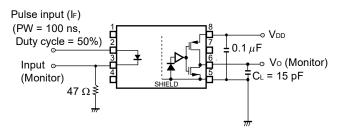
ELECTRICAL CHARACTERISTICS

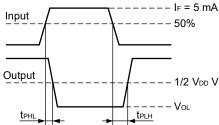
(T_A = - 40 to +110 °C, V_{DD} = 2.7 to 5.5 V, unless otherwise specified)

	Parameter	Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 6 mA, T _A = 25 °C	1.4	1.55	1.7	V
	Reverse Current	I _R	V _R = 3 V, T _A = 25 °C			10	μA
	Terminal Capacitance	Ct	V _F = 0 V, f = 1 MHz, T _A = 25 °C		30		pF
Detector	High Level Output Current	I _{DDH}	I _F = 0 mA		1.1	2	mA
	Low Level Output Current	I _{DDL}	I _F = 5 mA		1.0	2	
	High Level Output Voltage	Vон	$I_0 = -3.2 \text{ mA}, I_F = 0 \text{ mA}$	V _{DD} -1.0	V _{DD}		V
			$I_0 = -20 \mu\text{A}, I_F = 0 \text{mA}$	V _{DD} -0.1	V _{DD}		
	Low Level Output Voltage	Vol	Io = 3.2 mA, I _F = 5 mA		0.13	0.4	
			$I_0 = 20 \ \mu A, I_F = 5 \ mA$		0.001	0.1	
Coupled	Threshold Input Voltage (H to L)	IFHL	Vo < 0.4 V		1.8	3.8	mA
	Isolation Resistance	R _{I-O}	V _{I-O} = 1 kV _{DC} , RH = 40 to 60 %,	10 ¹¹			Ω
			T _A = 25 °C				
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz, T _A = 25 °C		0.6		pF
	Propagation Delay Time	t _{PHL}	$I_F = 5 \text{ mA} \Leftrightarrow 0 \text{ mA}$		36	60	ns
	(H to L)*2		V _{DD} = 3.3 V,5 V				
	Propagation Delay Time (L to H)*2	t _{РLН}	C _L = 15 pF		38	60	
	Pulse Width Distortion*2	PWD			2	20	
	Propagation Delay Skew	t _{PSK}				25	
	Rise Time	tr			5		
	Fall Time	t _f			5		
	Common Mode	[СМн]	$I_F = 0 \text{ mA}, V_O > 4 \text{ V(V}_{DD} = 5 \text{ V)},$	50	60		kV/μs
	Transient Immunity at		$V_0 > 2.3 \text{ V(V}_{DD} = 3.3 \text{ V)},$				
	High Level Output*3		V _{CM} = 1.5 kV, T _A = 25 °C				
	Common Mode	CM _L	I _F = 5 mA,	50	60		
	Transient Immunity at		$V_O < 0.4 \text{ V(V}_{DD} = 3.3 \text{ V, 5 V)},$				
	Low Level Output*3		V _{CM} = 1.5 kV, T _A = 25 °C				

Note2: 1. Typical values at T_A = 25 °C

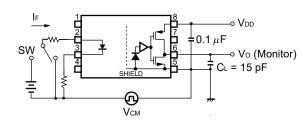
2. Test circuit for propagation delay time measurement

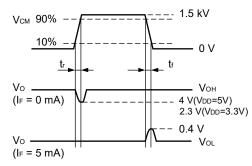




Remark C_L includes probe and stray wiring capacitance.

3. Test circuit for common mode transient immunity measurement



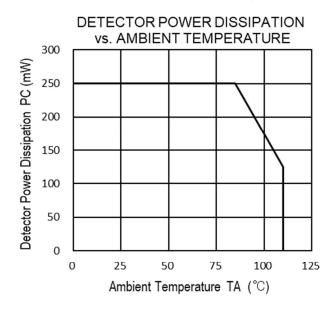


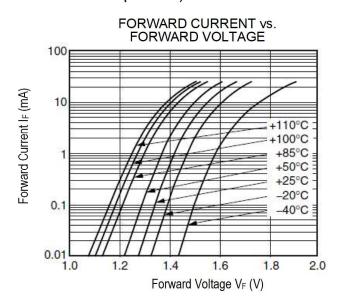
 $\label{eq:closed} \textbf{Remark} \qquad C_L \text{ includes probe and stray wiring capacitance}.$

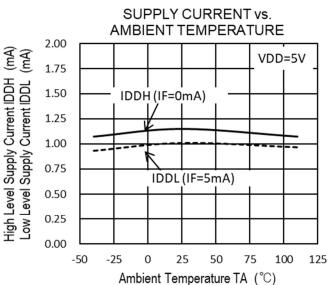
USAGE CAUTIONS

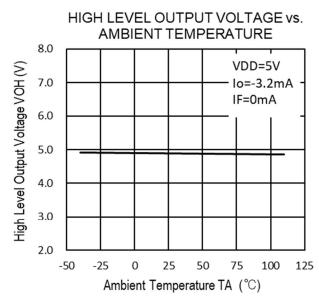
- 1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- **2.** By-pass capacitor of more than 0.1 μ F is used between V_{DD} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
- 3. Pin 1, 4 (which is an NC*1 pin) can either be connected directly to the GND pin on the LED side or left open. Also, Pin 7 (which is an NC*1 pin) can either be connected directly to the GND pin on the detector side or left open.
 - Unconnected pins should not be used as a bypass for signals or for any other similar purpose because this may degrade the internal noise environment of the device.
 - Note: *1. NC: Non-Connection (No Connection).
- 4. Avoid storage at a high temperature and high humidity.

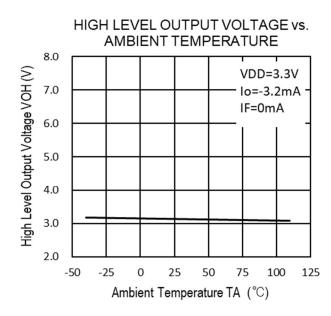
TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)

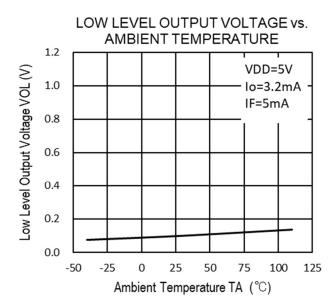




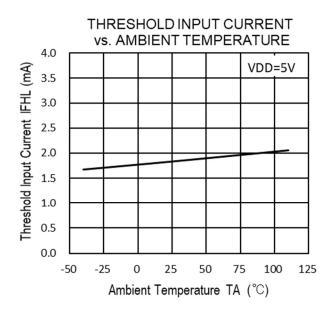


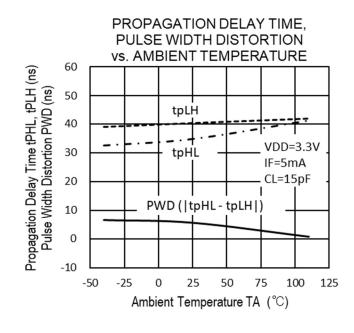


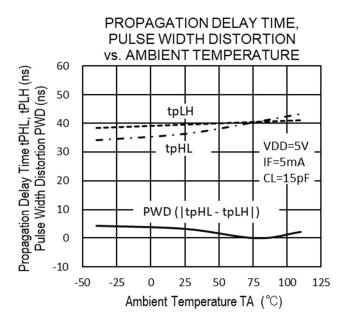


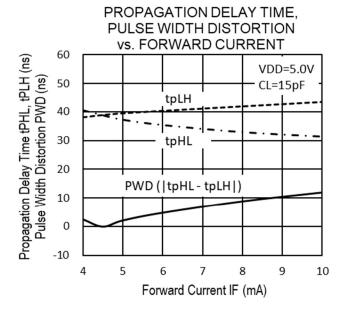


Remark The graphs indicate nominal characteristics.



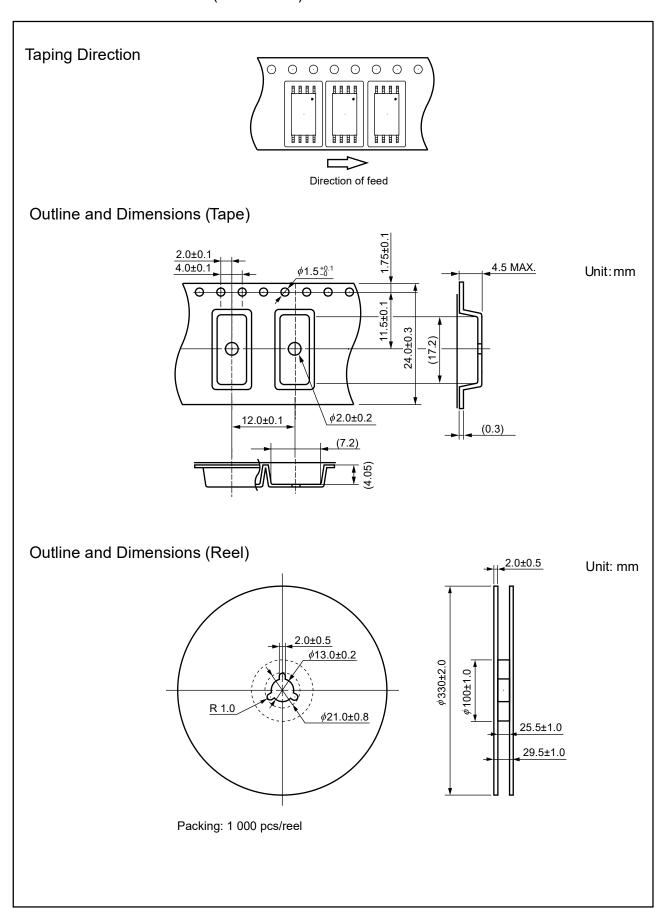




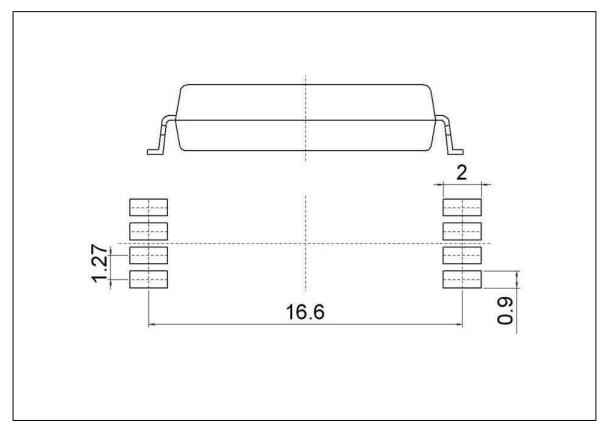


Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



[8pin LSDIP]

Remark All dimensions in this figure must be evaluated before use.

NOTES ON HANDLING

- 1. Recommended soldering conditions
 - (1) Infrared reflow soldering

 Peak reflow temperature 260 °C or below (package surface temperature)

• Time of peak reflow temperature 10 seconds or less Time of temperature higher than 220 °C 60 seconds or less

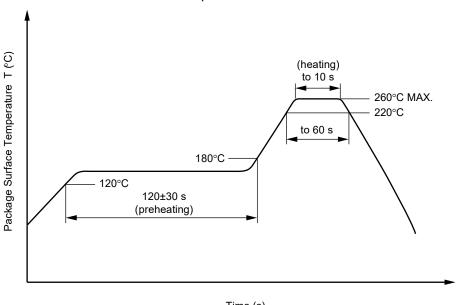
• Time to preheat temperature from 120 to 180 °C $\,$ 120 \pm 30 s

 Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of

0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

 Temperature 260 °C or below (molten solder temperature)

• Time 10 seconds or less

 Preheating conditions 120 °C or below (package surface temperature)

 Number of times One (Allowed to be dipped in solder including plastic mold portion.) Flux Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

 Peak Temperature (lead part temperature) 350 °C or below • Time (each pins) 3 seconds or less

• Flux Rosin flux containing small amount of chlorine

(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead
- (b) Please be sure that the temperature of the package would not be heated over 110 °C
- (4) Cautions
 - Flux Cleaning

Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.

• Do not use adhesives or coating materials including halogens to fix this device.

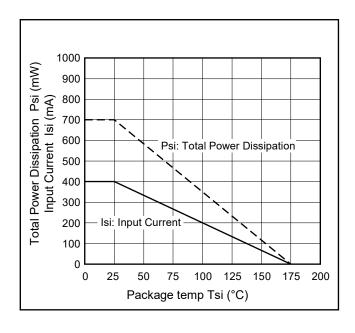
2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between V_{DD}-GND at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

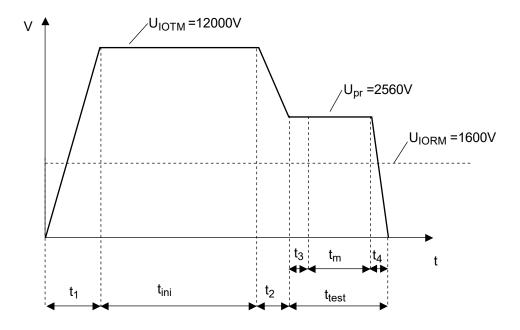
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/110/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.6 \times U_{\text{IORM}}, P_{\text{d}} < 5 \text{pC}$	Uiorm Upr	1 600 2 560	V _{peak} V _{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr}=1.875\times U_{IORM},P_d<5\;pC$	U_pr	3 000	V_{peak}
Highest permissible overvoltage	U _{ІОТМ}	12 000	V_{peak}
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	СТІ	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	Tstg	-55 to +125	°C
Operating temperature range	TA	-40 to +110	°C
Isolation resistance, minimum value VIO = 500 V dc at TA = 25°C VIO = 500 V dc at TA MAX. at least 100°C	Ris MIN. Ris MIN.	10 ¹² 10 ¹¹	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I _F , Psi = 0) Power (output or total power dissipation) Isolation resistance	Tsi Isi Psi	175 400 700	°C mA mW
V _{IO} = 500 V dc at T _A = Tsi	Ris MIN.	10 ⁹	Ω

Dependence of maximum safety ratings with package temperature



Method a Destructive Test, Type and Sample Test



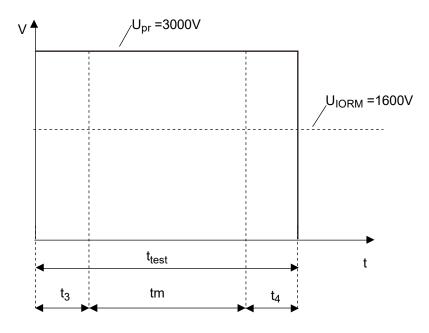
 $t_1, t_2 = 1 \text{ to } 10 \text{ sec}$

 $t_3, t_4 = 1 \text{ sec}$

 $t_{m(PARTIAL\ DISCHARGE)}$ = 10 sec t_{test} = 12 sec

 $t_{ini} = 60 \text{ sec}$

Non-destructive Test, 100% Production Test Method b



 $t_3, t_4 = 0.1 \text{ sec}$

 $t_{m(PARTIAL\ DISCHARGE)}$ = 1.0 sec

 $t_{test} = 1.2 sec$

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

All trademarks and registered trademarks are the property of their respective owners.

Notice

- 1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
- 2. Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
- 3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others
- 4. You shall be responsible for determining what licenses are required from any third parties, and obtaining such licenses for the lawful import, export, manufacture, sales, utilization, distribution or other disposal of any products incorporating Renesas Electronics products, if required.
- 5. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
- 6. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.
 - "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.
 - "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.

Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.

- 7. No semiconductor product is absolutely secure. Notwithstanding any security measures or features that may be implemented in Renesas Electronics hardware or software products, Renesas Electronics shall have absolutely no liability arising out of any vulnerability or security breach, including but not limited to any unauthorized access to or use of a Renesas Electronics product or a system that uses a Renesas Electronics product. RENESAS ELECTRONICS DOES NOT WARRANT OR GUARANTEE THAT RENESAS ELECTRONICS PRODUCTS, OR ANY SYSTEMS CREATED USING RENESAS ELECTRONICS PRODUCTS WILL BE INVULNERABLE OR FREE FROM CORRUPTION, ATTACK, VIRUSES, INTERFERENCE, HACKING, DATA LOSS OR THEFT, OR OTHER SECURITY INTRUSION ("Vulnerability Issues"). RENESAS ELECTRONICS DISCLAIMS ANY AND ALL RESPONSIBILITY OR LIABILITY ARISING FROM OR RELATED TO ANY VULNERABILITY ISSUES. FURTHERMORE, TO THE EXTENT PERMITTED BY APPLICABLE LAW, RENESAS ELECTRONICS DISCLAIMS ANY AND ALL WARRANTIES, EXPRESS OR IMPLIED, WITH RESPECT TO THIS DOCUMENT AND ANY RELATED OR ACCOMPANYING SOFTWARE OR HARDWARE, INCLUDING BUT NOT LIMITED TO THE IMPLIED WARRANTIES OF MERCHANTABILITY, OR FITNESS FOR A PARTICULAR PURPOSE.
- 8. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
- 9. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
- 10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
- 11. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
- 12. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
- 13. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
- 14. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.
- (Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.
- (Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Rev.5.0-1 October 2020)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

Contact information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit: www.renesas.com/contact/.